

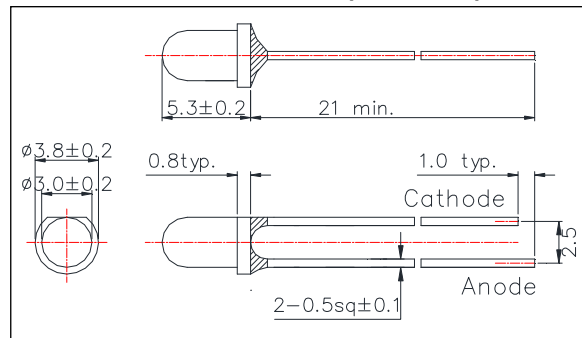
L940-33AU

Infrared LED Lamp

<Specifications>

- Chip Material: AlGaAs
- Chip Dimension: 400um x 400um
- Number of Chips: 1pcs
- Peak wavelength: 940nm Typ.
- Package Type: Φ3mm Clear Molding
- Lead Frame: Soldered (Lead Free)
- Lens: Epoxy Resin

Outer Dimension (Unit:mm)



Absolute Maximum Ratings[Tc=25°C]

Item	Symbol	Maximum Rated Value	Unit
Power Dissipation	PD	150	W
Forward Current	IF	100	A
Pulse Forward Current*	IFP	1000	
Reverse Voltage	VR	5	V
Thermal Resistance	Rthja	270	K/W
Junction Temperature	Tj	120	°C
Operating Temperature	TOPR	-40 ~ +100	°C
Storage Temperature	TSTG	-40 ~ +100	°C
Soldering Temperature**	TSOL	265	°C

* Duty=1% and Pulse Width=10us.

** Soldering condition must be completed within 3 second at 265 °C.

Electro-Optical Characteristics[Tc=25°C]

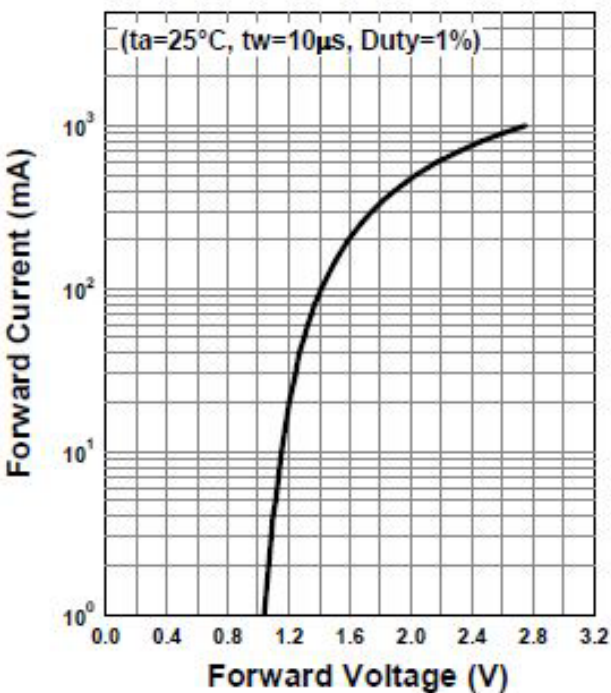
Item	Symbol	Condition	Min	Typ	Max	Unit
Forward Voltage	VF	IF=50mA		1.3	1.5	V
	VFP	IFP=1A		2.7		
Total Radiated Power*	PO	IF=50mA		15		mW
		IFP=1A		240		
Radiant Intensity**	IE	IF=50mA		44		mW/sr
		IFP=1A		700		
Peak Wavelength	λP	IF=50mA	930		950	nm
Half Width	Δλ	IF=50mA		50		nm
Viewing Half Angle	θ1/2	IF=50mA		±25		deg
Rise Time	tr	IF=50mA		1000		ns
Fall Time	tf	IF=50mA		1000		ns

* Measured by S3584-08

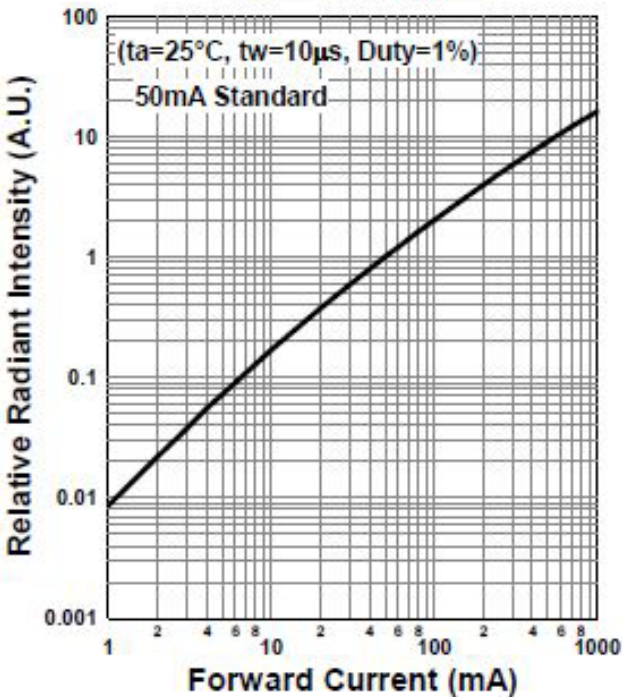
** Measured by CIE127-2007 Condition B



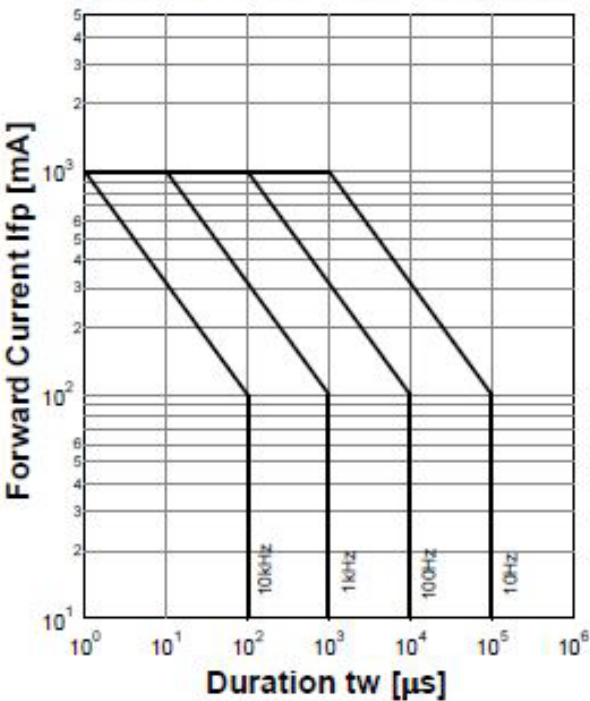
Forward Current - Forward Voltage



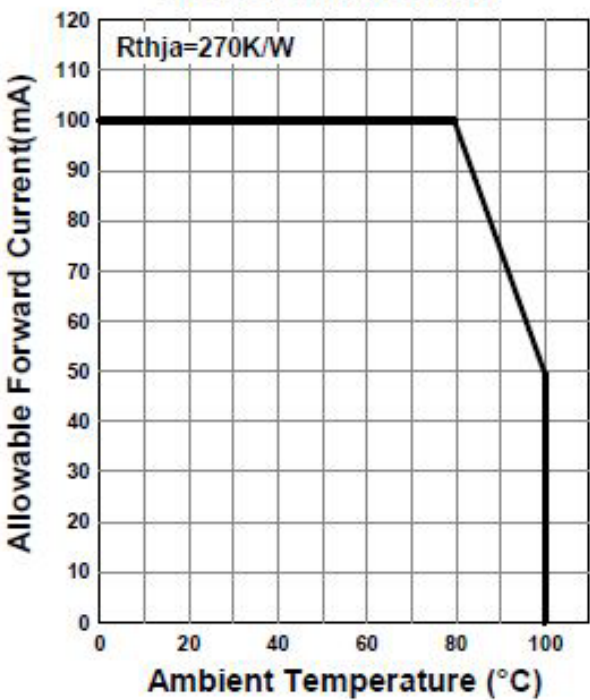
Relative Radiant Intensity - Forward Current

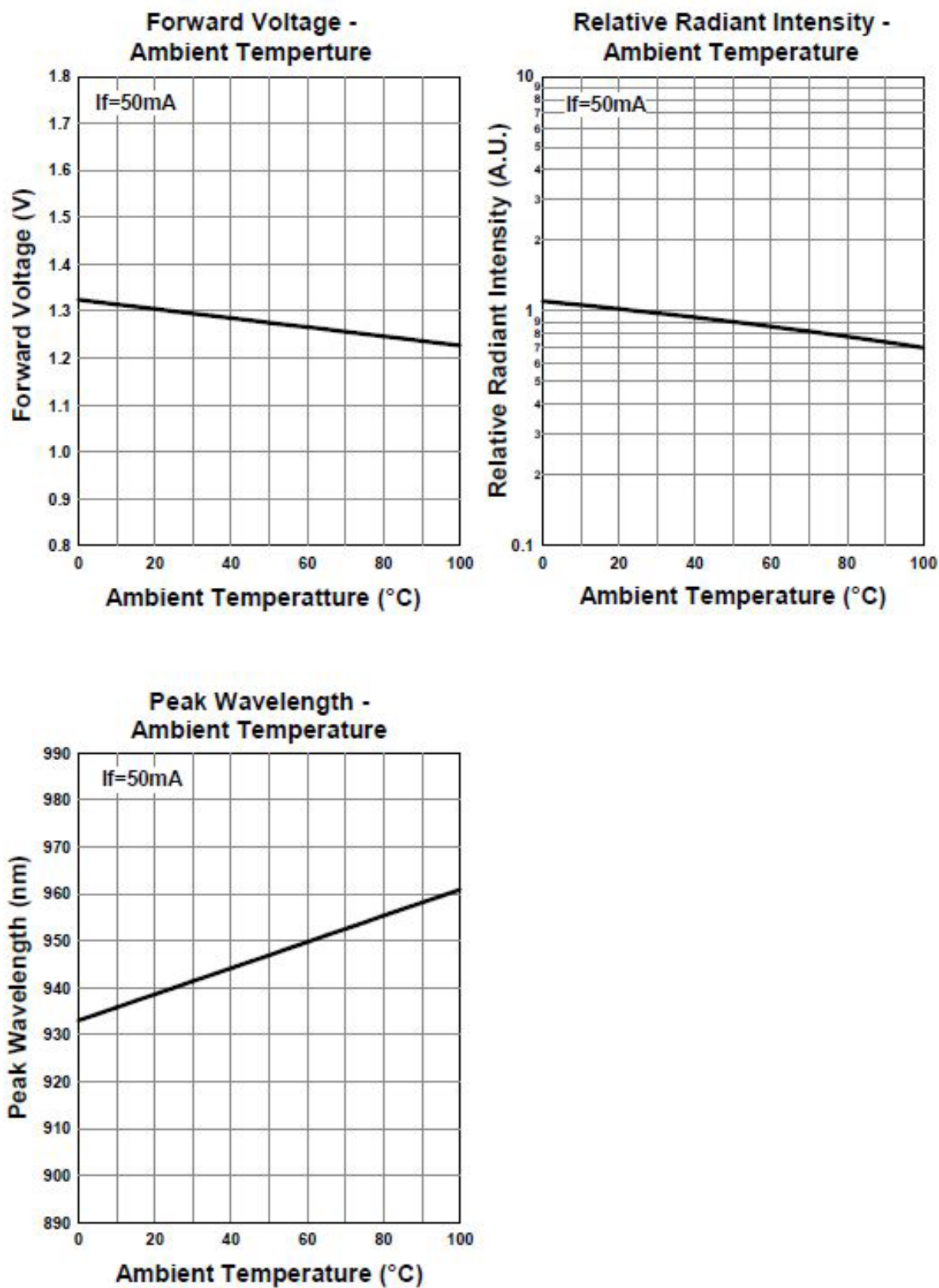


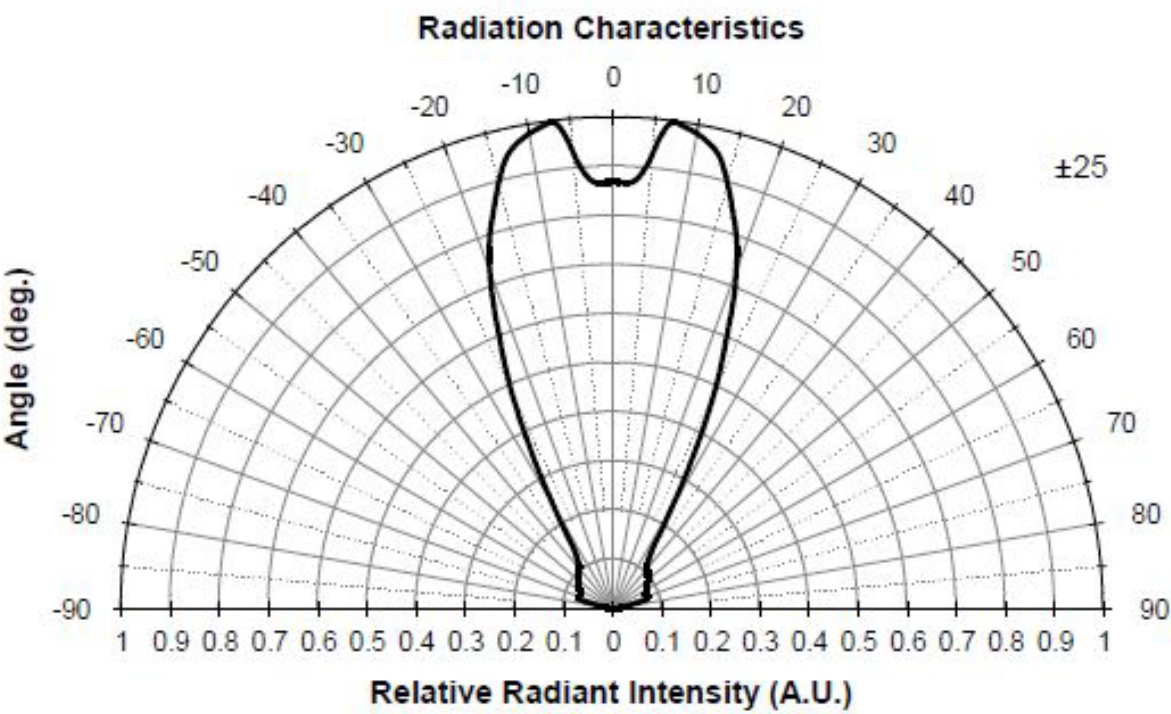
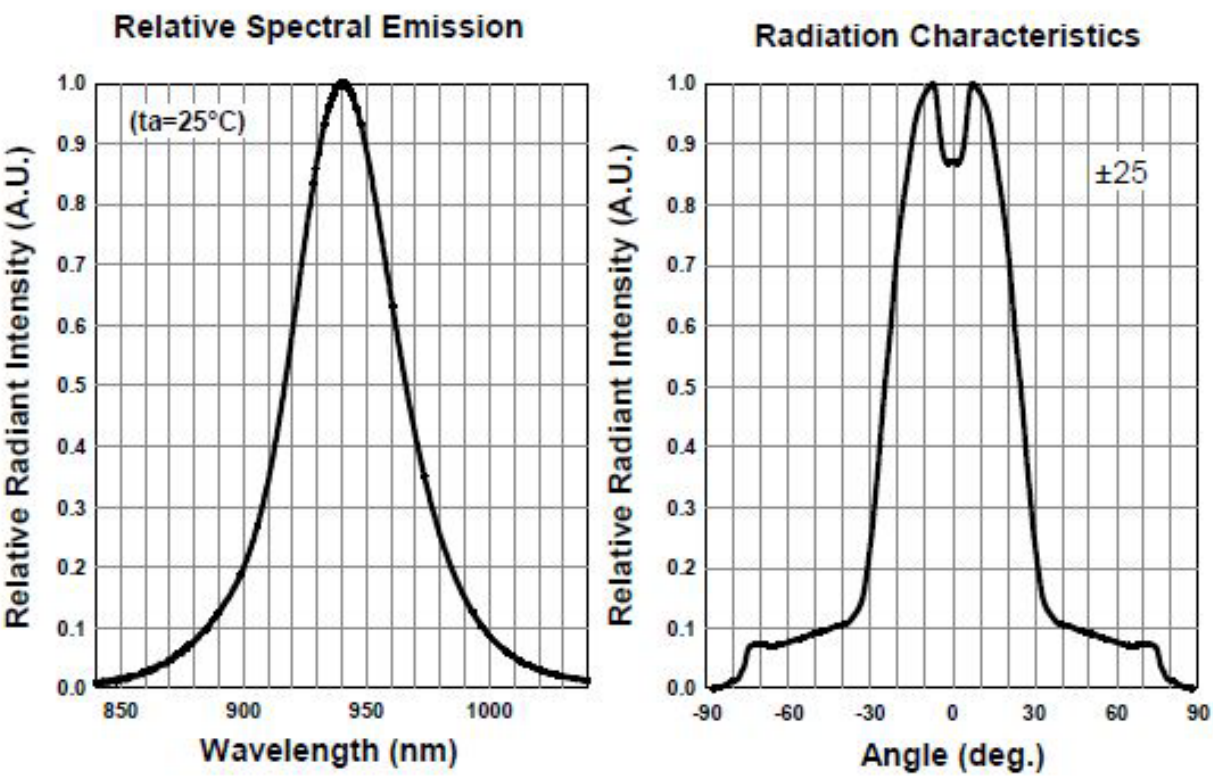
Forward Current - Pulse Duration



Allowable Forward Current - Ambient Temperature







Disclaimer

Product specifications and data shown in this product catalog are subject to change without notice for the purposes of improving product performance, reliability, design, or otherwise.

Product data and parameters in this catalog are typical values based on reasonably up-to-date measurements.

Product data and parameters may vary by user application and over time.

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